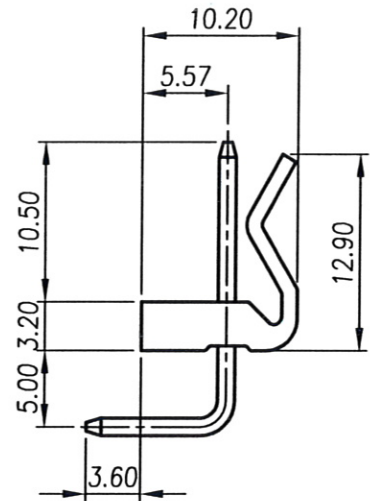
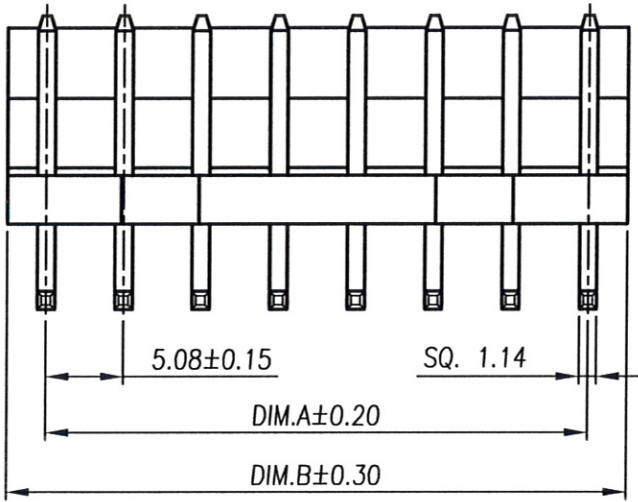
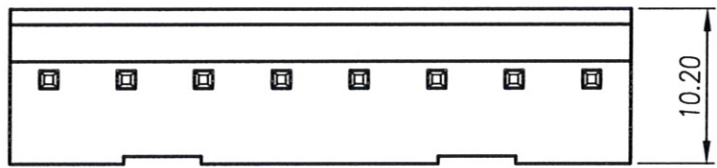


1 2 3 4 5 6 7 8

**RoHS Compliant**

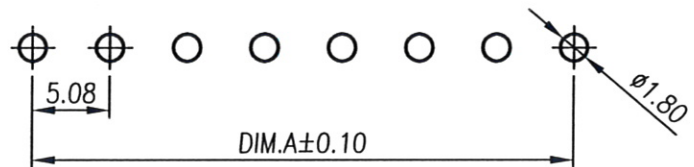
REV	MODIFICATION	DATE	DRAW
A0	Release To Production	2013.01.07	Michelle
A1	Release To ECN20141104	2014.11.06	Michelle



Specification  
 1.Current Rating:5A  
 2.Voltage Rating:250V AC/DC  
 3.Contact Resistance:20mΩ Max.  
 4.Insulation Resistance:1000MΩ Min. At DC 500V  
 5.Dielectric Withstanding Voltage:AC1500V/Minute  
 6.Operating Temperature:-25℃~+85℃

Material:  
 1.Housing:Thermoplastic UL94V-2  
 2.Contact Pin:Copper Alloy SQ. Pin 1.14mm  
 Finish:  
 1.Housing:Nature  
 2.Contact Pin:Bright Tin Plated Over Nickel  
 Part No.: AD00100 XX 0 1 5 2  
 Number Of Pin:  $\Delta I$  02~10  
 Packing: 5:Bag  
 Housing Material: 0:NY66 UL94V-2 Nature  
 Plating: 1:Bright Tin Plated Over Nickel

$\Delta I$	PIN	DIM.A	DIM.B	PIN	DIM.A	DIM.B
	02	5.08	10.22	07	30.48	35.62
	03	10.16	15.30	08	35.56	40.70
	04	15.24	20.38	09	40.64	45.78
	05	20.32	25.46	10	45.72	50.86
	06	25.40	30.54			



RECOMMENDED P.C.B LAYOUT  
 (TOLERANCE:±0.05)



		<b>金上達科技股份有限公司</b> GOLDENSUNDA TECHNOLOGY CO.,LTD				
		TOLERANCE UNLESS OTHERWISE SPECIFIED		PROJ.		TITLE: Wire To Board Wafer 5.08mm 90° DIP Single Row
.x± 0.35	x.*± 2'	APR. C.F.Liao 20141106	PART NO. AD00101XX0152		DWG NO. AD00101XX0152	
.xx± 0.25	.x*± 1'	CHK. Abel 20141106	UNITS: mm	<b>CUSTOMER DRAWING</b>		
.xxx± 0.15	.xx*± 0.5'	DRA. Michelle 20141106	SIZE: <b>A4</b>	SCALE: 2:1	SHEET 1 / 1	REV A1 V

1 2 3 4 5 6 7 8